

Technical Data Copper, pure and low-alloyed ¹⁾



		Copper	Oxygen-free Copper		Copper alloyed	
		Cu-ETP1	Cu-OF1	Cu-OF1 selekt. *	CuAg0,1 *	HCHS **
Material - No.	DIN / EN	CW003A	CW007A	-	CW013A	-
	UNS	C11040	C10100	-	C11600	-
Nominal Composition	[%]	≥ 99,95 Cu	≥ 99,99 Cu	≥ 99,99 Cu Incl. Ag	≥ 99,80 Cu Ag 0,1	≥ 99,60 Cu
Conductivity ²	[m/(Ohm mm ²)]	58	58	58	57	50
Conductivity ²	[% IACS]	100	100	100	98	86
Thermal Conductivity ²	[W/(mK)]	390	390	390	390	355
Coefficient of Thermal Expansion ³	[10 ⁻⁶ /K]	17	17	17	17	17
Tensile Strength annealed	[N/mm ²]	240	240	240	240	-
Elongation annealed	[%]	30	30	30	30	-
Tensile Strength hard	[N/mm ²]	450	450	450	450	600
Density	[g/cm ³]	8,9	8,9	8,9	8,9	8,9

1) Nominal data for diameter 0,8 mm

2) At 20° C

3) Temperature range 20 - 200° C

*) higher thermal resistance

***) excellent thermal resistance up to 600° C (High Conductivity High Strength)